

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Number 0340801001 Part Weight 0.363G

Part Name MX150 BLD CS TERM TIN 14/16AWG D WIND

Product Composition

| Name | Туре | CAS Number | Proportion (% Total) | Mass (Grams) |
|---------------------------------------|-----------|------------|-------------------------|-----------------|
| MX150 BLD CS TERM TIN 14/16AWG D WIND | Assembly | | 100 | 0.363 |
| MX150 BLD CS TERM TIN 14/16AWG B WIND | Component | | 100 | 0.363 |
| HSM Copper | Material | | 100 | 0.363 |
| HSM Copper Unplated | Material | | 98.8024 | 0.358653 |
| Copper | Substance | 7440-50-8 | 96.8758 | 0.351659 |
| Nickel | Substance | 7440-02-0 | 0.988 | 0.003587 |
| Tin | Substance | 7440-31-5 | 0.8892 | 0.003228 |
| Phosphorus | Substance | 7723-14-0 | 0.0494 | 0.000179 |
| Nickel Plating | Material | | 0.329 | 0.001194 |
| Nickel | Substance | 7440-02-0 | 0.329 | 0.001194 |
| Further Additives, not to declare | Substance | system | 3E-05 | 1E-07 |
| Tin Plating | Material | | 0.5396 | 0.001959 |
| Tin | Substance | 7440-31-5 | 0.5396 | 0.001959 |

Form Rev - F

Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

| Name | Туре | CAS Number | Proportion (% Total) | Mass (Grams) |
|----------------|-----------|------------|-------------------------|-----------------|
| Copper Plating | Material | | 0.329 | 0.001194 |
| Copper | Substance | 7440-50-8 | 0.329 | 0.001194 |

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Not reviewed

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

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| Substance Group | Substance Location | Threshold (PPM) | Concentration (PPM) | Intentionally Added |
|------------------------------------------|-------------------------------------------------------------|--------------------|---------------------|------------------------|
| lead | e-plate Sn (electrodeposited Tin Coatings, bright and matt) | *Note | 500 | Yes |
| nickel powder [particle diameter < 1 mm] | High Copper Alloy (NB109) | *Note | 10,000 | Yes |
| nickel powder [particle diameter < 1 mm] | Ep-Ni | *Note | 997,500 | Yes |
| silver | High Copper Alloy (NB109) | *Note | 500 | Yes |
| copper | High Copper Alloy (NB109) | *Note | 977,000 | Yes |
| copper | e-plate Cu (electrodeposited Copper Coatings) | *Note | 999,625 | Yes |

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

| Part Name | Exemption |
|-------------------------------------------------------------|----------------------------------------------------------------------------------------------|
| e-plate Sn (electrodeposited Tin Coatings, bright and matt) | 44 Concentration within acceptable GADSL limits |
| High Copper Alloy (NB109) | 34 Not applicable |
| Ep-Ni | 33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week) |

Process Information

| Component Plating / Surface Finish | N/A |
|--------------------------------------|-----|
| Termination Base Alloy | N/A |
| Solder Alloy | N/A |
| Process Capability | N/A |
| Maximum Exposure Time (seconds) | N/A |
| Maximum Process Temperature (C) | N/A |
| Maximum Cycles at Reflow Temperature | N/A |
| J-STD-020 Moisture Sensitivity Level | N/A |

Mar 24, 2021